

Automotive MOSFET

OptiMOS™ 7 Power-Transistor







Features

- OptiMOS[™] power MOSFET for automotive applications
- N-channel Enhancement mode Logic Level
- Extended qualification beyond AEC-Q101
- Enhanced electrical testing
- Robust design
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- · RoHS compliant
- 100% Avalanche tested



General automotive applications.



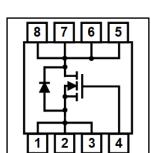
Qualified for automotive applications. Product validation according to AEC-Q101.

Product Summary

V_{DS}	100	V
R _{DS(on)}	28.9	mΩ
I _D (chip limited)	27	Α

Туре	Package	Marking
IAUZN10S7L289	PG-TSDSON-8-44	1B





IAUZN10S7L289



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Maximum Ratings

at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I _D	V _{GS} = 10 V, Chip limitation ^{1,2)}	27	А
		V _{GS} = 10 V, DC current	27	
		$T_a = 100^{\circ}\text{C}, V_{GS} = 10 \text{ V}, R_{thJA}$ on 2s2p ^{2,3)}	5	
Pulsed drain current ²⁾	I _{D,pulse}	$T_{\rm C} = 25^{\circ}{\rm C}, t_{\rm p} = 100 \mu{\rm s}$	54	7
Avalanche energy, single pulse ²⁾	E _{AS}	I _D = 9 A	11.8	mJ
Avalanche current, single pulse	I _{AS}	-	18	А
Gate source voltage	V_{GS}	-	±16	V
		Limited to duty factor of 1%	+20	7
Power dissipation	P_{tot}	T _C = 25°C	45	W
Operating temperature	$T_{\rm j}$	-	-55 +1 75	°C

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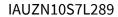
Thermal Characteristics²⁾

Paramatar	Cumbal	Conditions		Values		
Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	_	_	3.3	K/W
Thermal resistance, junction - ambient ³⁾	R_{thJA}	-	_	41.0	-	

Electrical Characteristics

at T_i=25 °C, unless otherwise specified

Parameter	Sumah al	Sandal Sanditions	Values					
	Symbol	Conditions	min.	typ.	max.	Unit		
Static Characteristics								
Drain-source breakdown voltage	V _{(Br)DSS}	$V_{GS} = 0 \text{ V},$ $I_D = 1 \text{ mA}$	100	-	-	V		
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 9 \mu A$	1.2	1.6	2.0			
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 25^{\circ}\text{C}$	-	-	1	μА		
Zero gate voltage drain current	/ DSS	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V},$ $T_j = 100^{\circ}\text{C}^{2j}$	-	_	3			
Gate-source leakage current	I _{GSS}	$V_{GS} = 16 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	100	nA		
		$V_{GS} = 4.5 \text{ V}, I_D = 14 \text{ A}$	_	28.9	38.5	mΩ		
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 14 A	_	25.8	28.9			
Gate resistance ²⁾	R _G	-	_	1.2	-	Ω		





Parameter	Symbol Conditions	Values			IImia		
	Symbol		min.	typ.	max.	Unit	
Dynamic Characteristics ²⁾							
Input capacitance	Ciss		_	428	557	pF	
Output capacitance	C oss	$V_{GS} = 0 \text{ V}, V_{DS} = 50 \text{ V}, f = 1 \text{ MHz}$	_	180	234		
Reverse transfer capacitance	C _{rss}		-	5	8		
Turn-on delay time	t _{d(on)}		-	1.6	-	ns	
Rise time	t _r	$V_{DD} = 50 \text{ V}, V_{GS} = 10 \text{ V},$ $I_{D} = 14 \text{ A}, R_{G} = 3.5 \Omega$	_	1.2	-		
Turn-off delay time	t _{d(off)}		_	9.1	_		
Fall time	t _f		_	2.6	_		

Gate Charge Characteristics2)

Gate to source charge	Q _{gs}		-	1.4	1.8	nC
Gate to drain charge	Q _{gd}	$V_{DD} = 50 \text{ V}, I_D = 14 \text{ A},$	-	1.5	2.3	
Gate charge total	Qg	$V_{DD} = 50 \text{ V}, I_{D} = 14 \text{ A},$ $V_{GS} = 0 \text{ to } 10 \text{ V}$	-	10.9	14.2	
Gate plateau voltage	V _{plateau}		-	3.2	-	V

Reverse Diode

Diode continuous forward current ²⁾	Is	T _C = 25°C	ı	ı	27	А
Diode pulse current ²⁾	I _{S,pulse}	$T_{\rm C} = 25^{\circ}{\rm C}, t_{\rm p} = 100 \mu{\rm s}$	ı	ı	54	
Diode forward voltage	V _{SD}	$V_{GS} = 0 \text{ V}, I_F = 14 \text{ A}, T_j = 25^{\circ}\text{C}$	ı	0.9	1.0	V
Reverse recovery time ²⁾	t _{rr}	$V_R = 50 \text{ V}, I_F = 27 \text{ A}$	-	21	32	ns
Reverse recovery charge ²⁾	Q _{rr}	$di_F/dt = 100 A/\mu s$	ı	8	16	nC

 $^{^{1)}}$ Practically the current is limited by the overall system design including the customer-specific PCB.

²⁾ The parameter is not subject to production testing – specified by design.

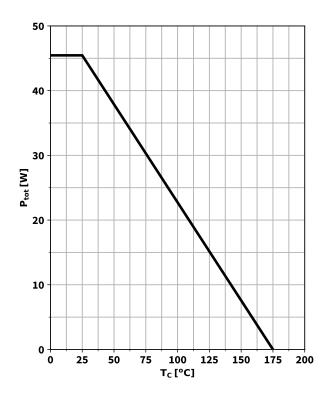
 $^{^{3)}}$ Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.



Electrical characteristics diagrams

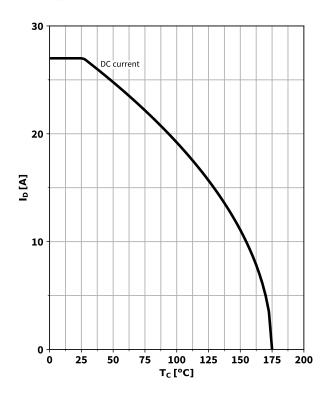
1 Power dissipation

 $P_{\text{tot}} = f(T_{\text{C}}); V_{\text{GS}} \ge 6 \text{ V}$



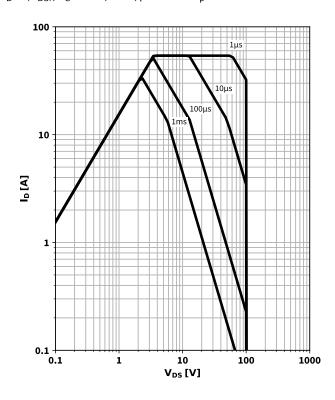
2 Drain current

 $I_{\text{D}} = f(T_{\text{C}}); V_{\text{GS}} \ge 6 \text{ V}$



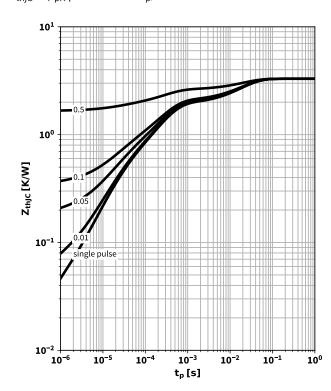
3 Safe operating area

 I_D = f(V_{DS}); T_C = 25 °C; D = 0; parameter: t_p



4 Max. transient thermal impedance

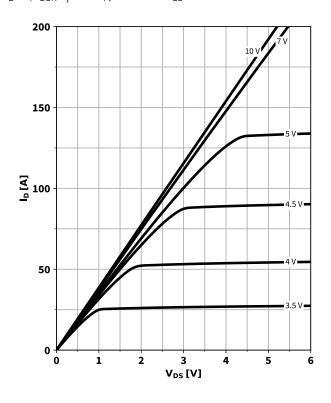
 $Z_{\text{thJC}} = f(t_p)$; parameter: D = t_p/T





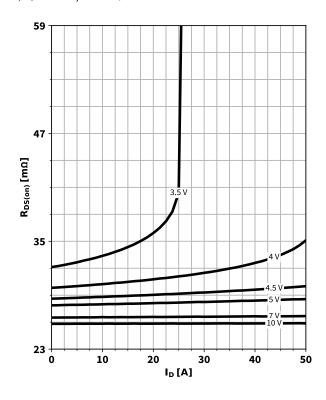
5 Typ. output characteristics

 $I_D = f(V_{DS}); T_j = 25 \,^{\circ}\text{C}; \text{ parameter: } V_{GS}$



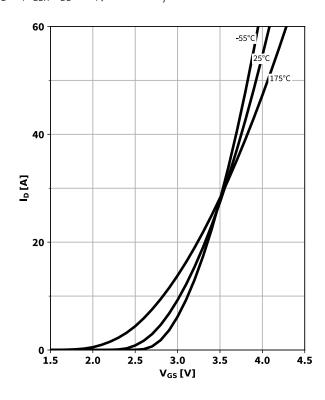
6 Typ. drain-source on-state resistance

 $R_{\mathrm{DS(on)}} = \mathrm{f}(I_{\mathrm{D}}); T_{\mathrm{j}} = 25 \, ^{\circ}\mathrm{C}; \mathrm{parameter}: V_{\mathrm{GS}}$



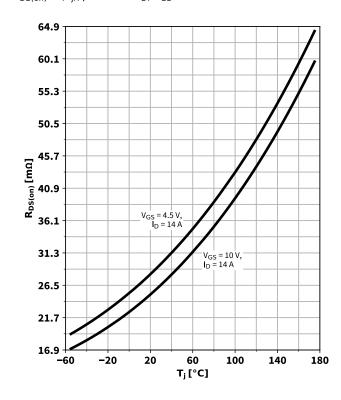
7 Typ. transfer characteristics

 $I_D = f(V_{GS}); V_{DS} = 6 \text{ V}; \text{ parameter: } T_j$



8 Typ. drain-source on-state resistance

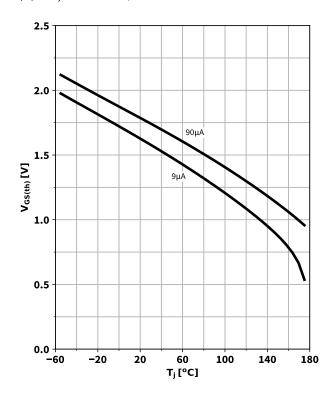
 $R_{DS(on)} = f(T_j)$; parameter: I_D , V_{GS}





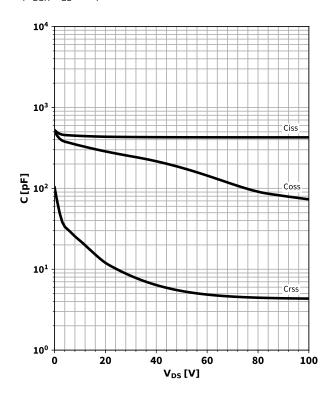
9 Typ. gate threshold voltage

 $V_{\text{GS(th)}} = f(T_{\text{j}}); V_{\text{GS}} = V_{\text{DS}}; \text{ parameter: } I_{\text{D}}$



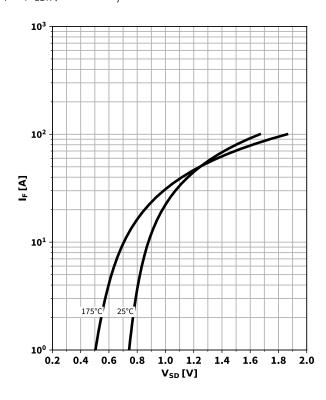
10 Typ. capacitances

 $C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$



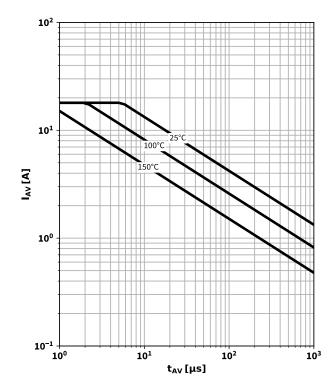
11 Typ. forward diode characteristics

 $I_F = f(V_{SD})$; parameter: T_j



12 Typ. avalanche characteristics

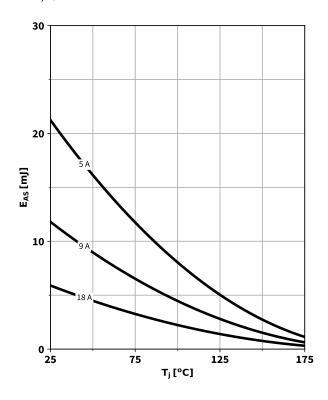
 $I_{AS} = f(t_{AV})$; parameter: $T_{j(start)}$





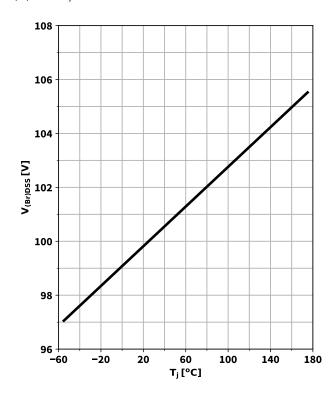
13 Typical avalanche energy

 $E_{AS} = f(T_j)$; parameter: I_D



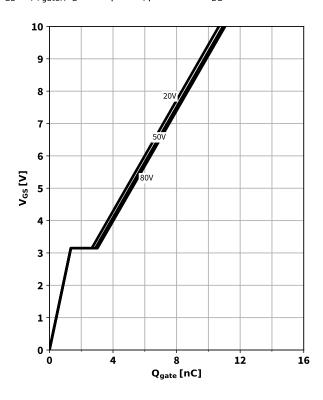
14 Drain-source breakdown voltage

 $V_{(Br)DSS} = f(T_j); I_D = 1 \text{ mA}$

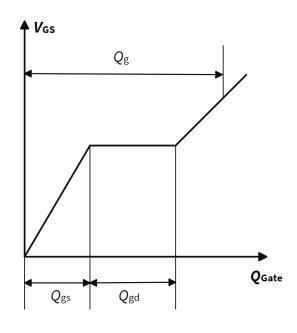


15 Typ. gate charge

 $V_{\rm GS}$ = f($Q_{\rm gate}$); $I_{\rm D}$ = 14 A pulsed; parameter: $V_{\rm DD}$



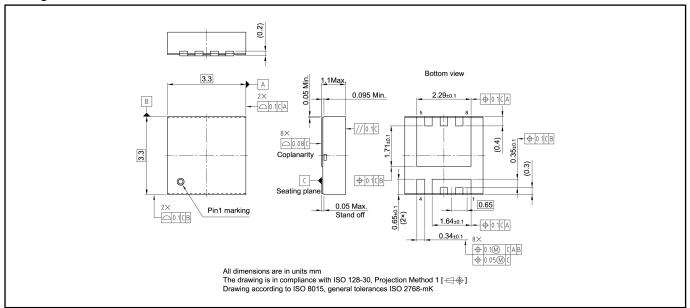
16 Gate charge waveforms



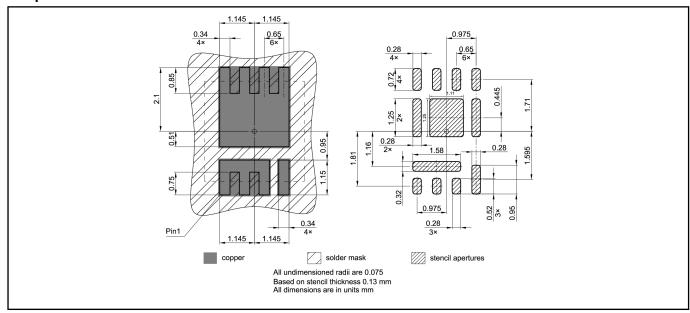
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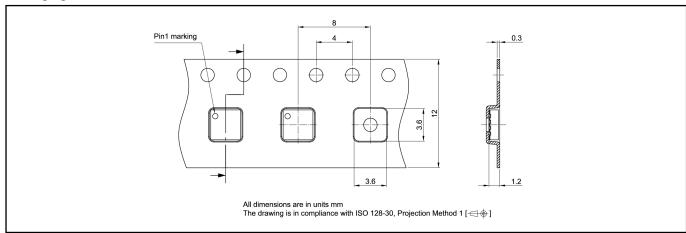
Package Outline



Footprint



Packaging



IAUZN10S7L289



Revision History

Revision	Date	Changes
Revision 1.0	2025-04-24	Final data sheet

Trademarks

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